FORM PTO-1083 (modified)

Case Docket No. 15.32 5685

In re the Application of:)
KOMIYAMA et al.)
Serial No. 09 776,528)
Filed: February 4, 2001)
For: METHODS FOR MANUFACTURING SEMICONDUCTOR CHIPS, METHODS FOR MANUFACTURING SEMICONDUCTOR DEVICES, SEMICONDUCTOR CHIPS, SEMICONDUCTOR DEVICES, CONNECTION SUBSTRATES AND ELECTRONIC DEVICES)

Group Art Unit: 2814

Examiner: Ha, Nathan W.

ASSISTANT COMMISSIONER OF PATENTS
Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

___ Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.

___ A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.

___ It is believe that no additional fee is required.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO PREVIOUSLY PAID FOR		PRESENT EXTRA RATE		ADDIT. FEE	OR	RATE	ADDIT. FEE
TOTAL	23	MINUS	23	=	0	x	$9	OR	x 18	$0
INDEP CLAIMS *	6	MINUS	7	=	0	x	$42	OR	x 84	$0
____ FIRST PRESENTATION OF MULTIPLE DEP. CLAIM						+	$140	OR	+ 280	$0
					TOTAL		$0	OR	TOTAL	$0

___ Please charge Deposit Account No. 50-0585 the amount of $___ to cover the extension fee and also the amount of $___ to cover the claim fee. A duplicate copy of this sheet is enclosed.

_X_ A check in the amount of $ 110 to cover the extension fee is enclosed.

___ A check in the amount of $ _____ to cover the filing fee for additional claims is enclosed.

_X_ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. No. 50-0585. A duplicate of this sheet is enclosed.

_X_ Any filing fees under 37 CFR 1.16 for the presentation of extra claims.

_X_ Any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

Alan S. Raynes

Dated: March 31, 2003

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Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on March 31, 2003.

Alan S. Raynes — March 31, 2003

Alan S. Raynes — **Date**

15.32/5685

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:	Group Art Unit: 2814
KOMIYAMA et al.	
Serial No. 09/776,528	Examiner: Ha, Nathan W.
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For: METHODS FOR MANUFACTURING SEMICONDUCTOR CHIPS, METHODS FOR MANUFACTURING SEMICONDUCTOR DEVICES, SEMICONDUCTOR CHIPS, SEMICONDUCTOR DEVICES, CONNECTION SUBSTRATES AND ELECTRONIC DEVICES	**AMENDMENT**

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sirs:

In response to the Office Action dated Nov. 29, 2002, the response due date being extended to Monday, March 31, 2003 (March 29 was a Saturday) by the enclosed petition for extension of time, please enter and consider the following.

IN THE CLAIMS:

Please cancel claims 9-22 without prejudice.

Please amend claims 4-5, 7-8 and 23 as follows:

4. (amended) A method for manufacturing a semiconductor chip, the method comprising: forming an electrode on a surface of a first semiconductor chip and thereafter forming a hole from another surface of the first semiconductor chip until the electrode is exposed, forming a protrusion by etching a surface of a second semiconductor chip and thereafter forming an abutting electrode on an apex section of the protrusion, and positioning the first semiconductor chip and the second semiconductor chip such that the abutting electrode is in electrical contact with the electrode.